

MULTI-LAYER POLYMER-SOLDER HYBRID
THERMAL INTERFACE MATERIAL
FOR INTEGRATED HEAT SPREADER
AND METHOD OF MAKING SAME

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ABSTRACT OF THE DISCLOSURE

A process of making a multi-layer thermal interface material is depicted.
The multi-layer thermal interface material is attached between an integrated heat
spreader and a die. Processing of the multi-layer thermal interface material includes
10 stamping or other pressure processing.

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